



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



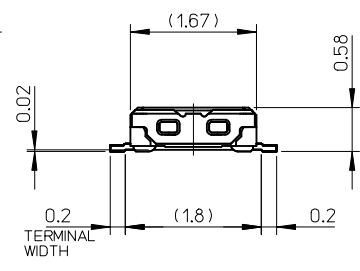
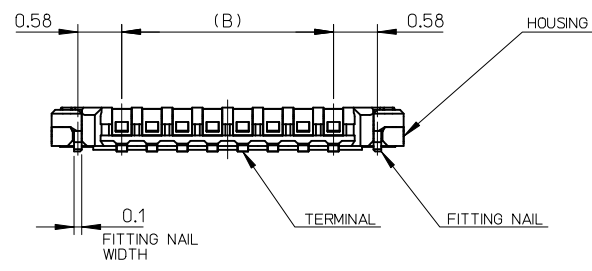
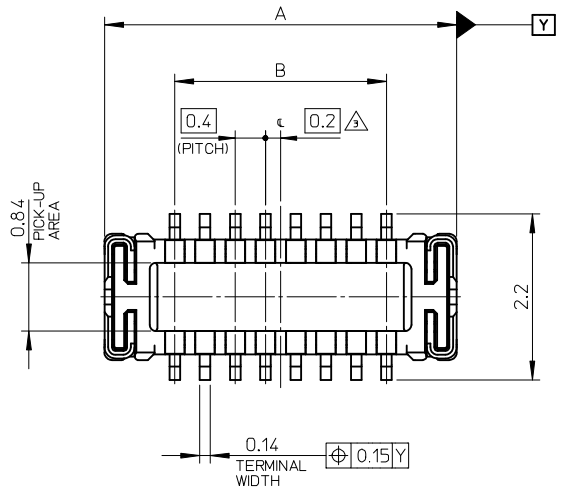
## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



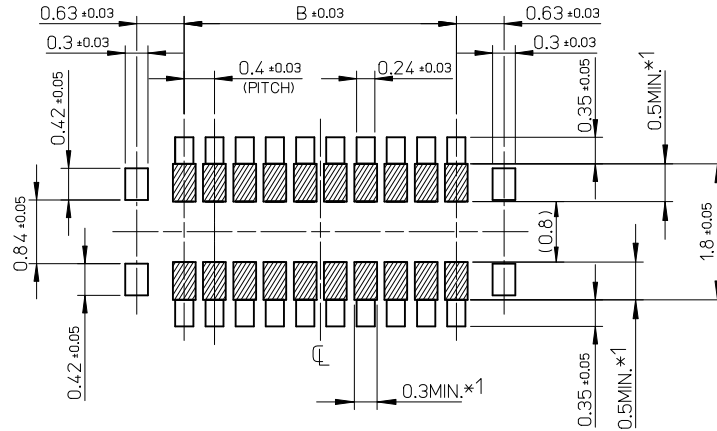


注記 NOTES

1. 使用材料 MATERIAL  
 ハウジング : 液晶ポリマー ( LCP ) UL94V-0 ( 黒 )  
 HOUSING: LIQUID CRYSTAL POLYMER UL94V-0 (COLOR:BLACK)  
 ターミナル : 銅合金  
 TERMINAL : COPPER ALLOY  
 金具 : 銅合金  
 FITTING NAIL : COPPER ALLOY
2. メッキ仕様 PLATING  
 ターミナル TERMINAL  
 金メッキ  
 GOLD  
 下地メッキ : ニッケルメッキ  
 UNDER PLATING : NICKEL  
 ※コンタクト部とテール部はニッケルメッキによって分断されている金メッキです。  
 DIVIDE INTO PARTS THE GOLD PLATING OF THE CONTACT AND THE TAIL PART BY THE NICKEL PLATING.  
 金具 FITTING NAIL  
 金メッキ (テール部のみ)  
 GOLD (ONLY TAIL PART)  
 下地メッキ : ニッケルメッキ  
 UNDER PLATING : NICKEL
- △ (全極数 / 2) = 偶数の場合に適用。  
 APPLY FOR (CIRCUIT/2)=EVEN.
4. 嵌合相手 : 503548 シリーズ  
 MATE WITH : 503548 SERIES.
5. テール平坦度は、0.08 以下  
 テール及び金具の平坦度は、0.1 以下  
 TAIL COPLANARITY TO BE 0.08MAXIMUM.  
 TAIL AND FITTING NAIL COPLANARITY TO BE 0.1MAXIMUM.

3.2	5.06	503552-1820	18
2.8	4.66	503552-1620	16
2.4	4.26	503552-1420	14
2.0	3.86	503552-1220	12
1.6	3.46	503552-1020	10
0.8	2.66	503552-0620	6
B	A	EMBOSSED PACKAGE	極数
		オーダー番号 ORDER No.	CIRCUITS
CONNECTOR SERIES No. : 503552-***19			

REVISED EC NO: J2013-1507 DRWN:YFUJIMAKI 2013/06/13 CHKD:TASAKAWA 2013/06/13 APPR:KMORIKAWA 2013/06/14	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY RTAKEUCHI	DATE 2010/04/08	TITLE 0.4 B-T0-B CONN HGT=0.7 W=2.6 HI-RETENTION PLUG ASSY			
		10 OVER 30 UNDER	±0.25	CHECKED BY THIRATA	DATE 2010/04/08				
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 2010/09/15				
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-503552-005		SHEET NO. 1 OF 2	
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



\*1 パターン引き回し、および半田禁止エリア  
 (当該箇所においては、これと接する回路以外の配線を禁止する。  
 また、接する回路を配線する場合はレジストを施し、この部分に  
 半田は無きこととする。)

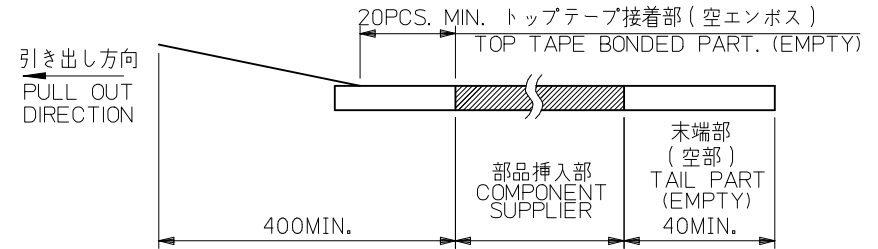
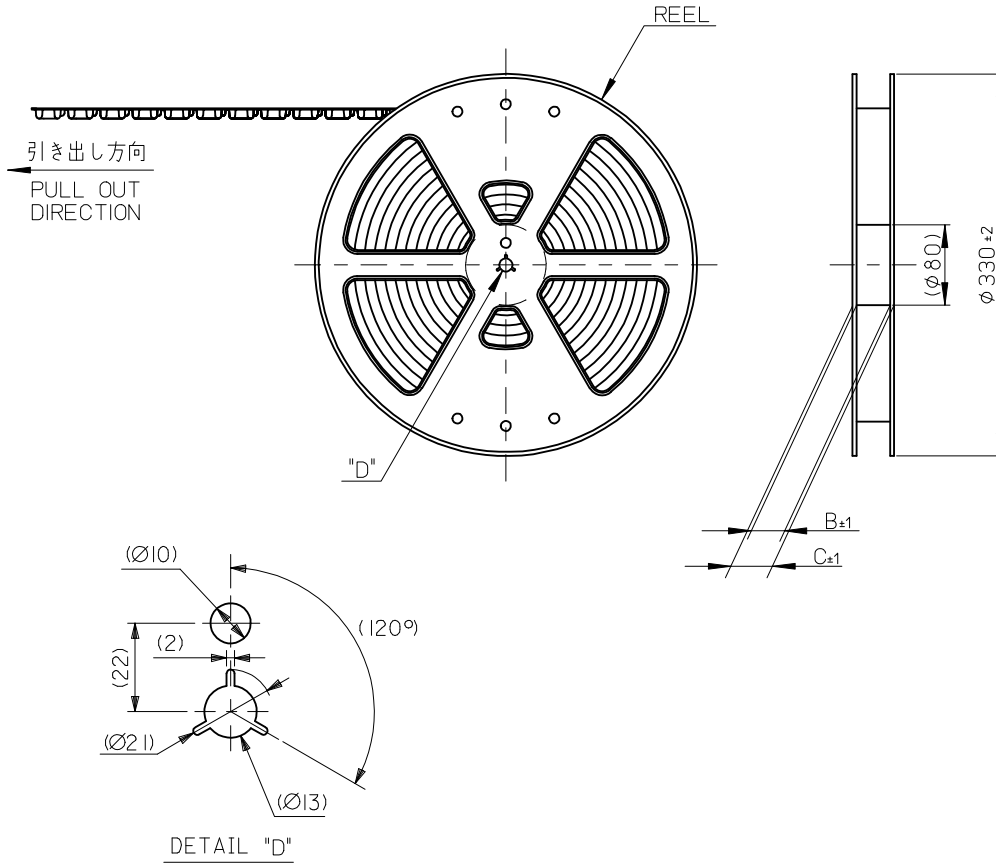
\*1 PROHIBITED AREA OF PATTERN WIRING AND SOLDER.  
 (FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER  
 CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)

RECOMMENDED P.W. BOARD  
 PATTERN LAYOUT

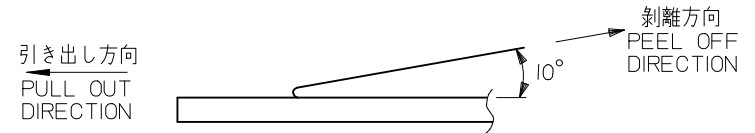
REVISED EC NO: J2013-1507 DRWN: FUJIMAKI 2013/06/13 CHKD: TASAKAWA 2013/06/13 APPR: KMORIKAWA 2013/06/14	DESCRIPTION A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 15:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY RTAKEUCHI	DATE 2010/04/08	TITLE 0.4 B-TO-B CONN HGT=0.7 W=2.6 HI-RETENTION PLUG ASSY			
		10 OVER 30 UNDER	± 0.25	CHECKED BY THIRATA	DATE 2010/04/08				
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2010/09/15				
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-503552-005		SHEET NO. 2 OF 2	
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							

注記 NOTES

- 製品詳細寸法については製品単体図面を参照下さい。  
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量：3000 個/リール  
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH

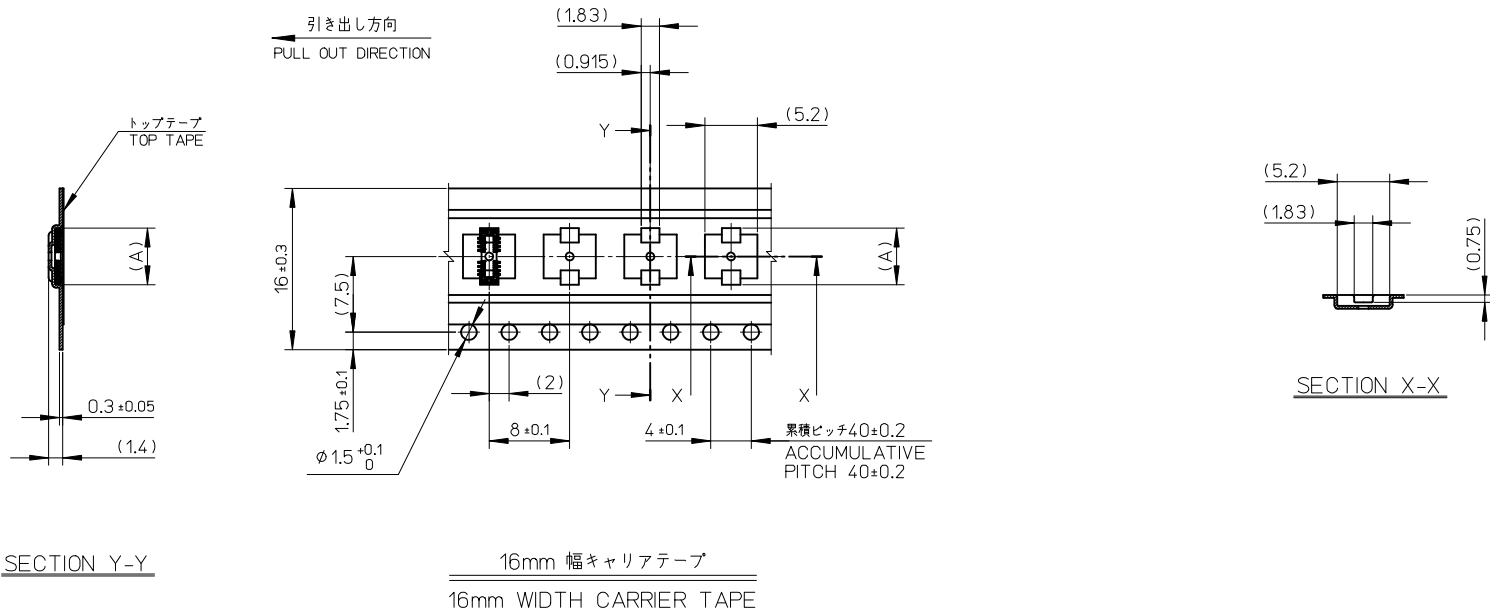


- トップテープの剥離強度：0.1N~1.3N(10gf~130gf)  
(剥離方向は下図参照)  
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE : 0.1N~1.3N(10gf~130gf)  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.  
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.



- 材料 MATERIAL  
キャリアテープ (CARRIER TAPE) : ポリスチレン (POLYSTYRENE)  
トップテープ (TOP TAPE) : PET , OTHER  
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>  
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- ELV 及び RoHS適合品  
ELV AND RoHS COMPLIANT

REVISED EC NO: J2013-1507 DRWN: YUJIMAKI 2013/06/13 CHKD: TASAKAWA 2013/06/13 APPR: KMORIKAWA 2013/06/14	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	MODEL NO. 503552-**20	
		10 UNDER	±---	DRAWN BY RTAKEUCHI		DATE 2010/02/08	TITLE 0.4 B-TO-B CONN. HGT=0.7 HI-RETENTION PLUG ASSY EMBSTP PKG
		10 OVER 30 UNDER	±---	CHECKED BY THIRATA		DATE 2010/02/08	
		30 OVER	±---	APPROVED BY MSASAO		DATE 2010/02/08	
A	ANGULAR ±---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-503552-006	SHEET NO. 1 OF 2
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



16	21.4	17.4	5.21	503552-1820	18
			4.81	503552-1620	16
			4.41	503552-1420	14
			4.01	503552-1220	12
			3.61	503552-1020	10
			2.81	503552-0620	6
キャリアテープ幅 CARRIER TAPE WIDTH			C	B	(A)
			MATERIAL No.		CKT.
			MODEL No.	503552-***20	

REVISED EC NO: J2013-1507 DRWN: FUJIMAKI 2013/06/13 CHKD: TASAKAWA 2013/06/13 APPR: MORIKAWA 2013/06/14	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER ± --- 10 OVER 30 UNDER ± --- 30 OVER ± --- ANGULAR ± --- °	DRAWN BY DATE RTAKEUCHI 2010/02/08		TITLE 0.4 B-TO-B CONN. HGT=0.7 HI-RETENTION PLUG ASSY EMBSTP PKG		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY DATE THIRATA 2010/02/08		APPROVED BY DATE MSASAO 2010/02/08		
			MATERIAL NO. SEE CHART		DOCUMENT NO. SD-503552-006		SHEET NO. 2 OF 2